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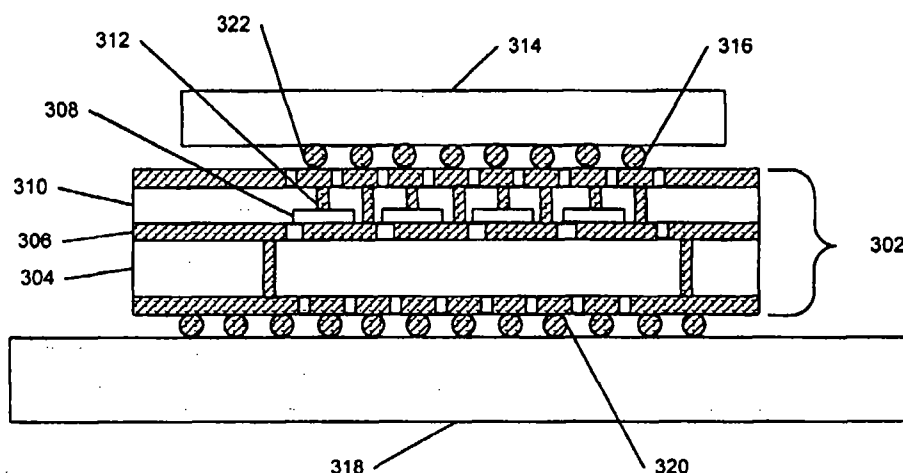
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(54) Title: **ELECTRONIC PACKAGE HAVING EMBEDDED CAPACITORS AND METHOD OF FABRICATION THEREFOR**



(57) Abstract: An electronic package (302, Figure 3) includes one or more capacitors (308) embedded within one or more layers (310) of the package. The embedded capacitors are discrete devices, such as integrated circuit capacitors (Figures 17-18) or ceramic capacitors. During the package build-up process, the capacitors are mounted (410, Figure 4) to a package layer, and a non-conductive layer is applied (412) over the capacitors. When the build-up process is completed, the capacitor's terminals (604, 608, Figure 6) are electrically connected to the top surface of the package. The embedded capacitor structure can be used in an integrated circuit package (1904, Figure 19), an interposer (1906), and/or a printed circuit board (1908).

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